

2023/10

ADEKA REMYLOP FL-494

■ Product Features

- One-component heat curing adhesive
- High thermal resistance
- Epoxy type (Halogen-free available)
- Low CTE (coefficient of thermal expansion)

■ Properties (uncured)

Viscosity / 25°C	0.5 rpm	203	Pa · s
	5 rpm	85	Pa · s
Thixotropic value	0.5 rpm/5 rpm	2.4	
Specific gravity		1.75	
Filler content		73	wt %
Nonvolatile content		> 99	%
Pot Life	25 °C	168	hrs
Shelf Life	≤ 5 °C	4	months
Viscosity / 25°C	≤ -18 °C	12	months

■ Cured Material Properties

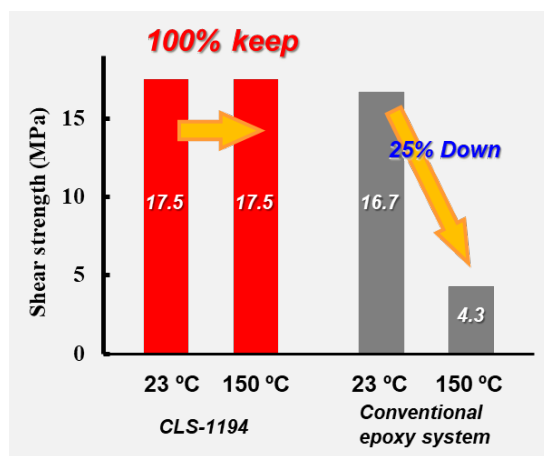
Glass transition temperature	TMA	211	°C
	DMA	241	°C
Hardness	ShoreD	> D80	
Storage modulus/ 25°C	DMA	1.2	GPa
Coefficient of linear expansion	α _l	16	ppm
Thermal conductivity	Transient hot wire method	0.6	W/m · K

DSC : SH DCS6220 25 – 300 °C (10 °C/min)
 DMA : TA RSA-G2 25 – 300 °C (10 °C/min),
 curing condition ; 180 °C × 1 hr
 TMA : SH TMA/SS6100 25 – 300 °C (5 °C/min),
 curing condition ; 180 °C × 1 hr

■ Recommended Curing Conditions

150	°C	1	hr
180		0.5	hr

■ Adhesion (Based on CLS-1194)



Fe/Fe Shear adhesion test (180 °C × 1 hr)

■ Usage

- 【Storage】 Store in a sealed container at temperature below 5 °C (-18 °C recommended)
- 【Breaking the seal】 To prevent moisture condensation, please bring the product to room temperature before opening the package.
- 【Curing】 The adhesive must be heated sufficiently to reach the curing temperature. Curing conditions vary depending on the thermal capacity of the adherend and surrounding parts, the method of use, and the amount of coating applied.
- 【Disposal】 Please refer to SDS for proper treatment.
- 【Others】 Please contact us at the following

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